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Lead-free Green

DGD2190M

HIGH-SIDE AND LOW-SIDE GATE DRIVER IN SO-8

Description

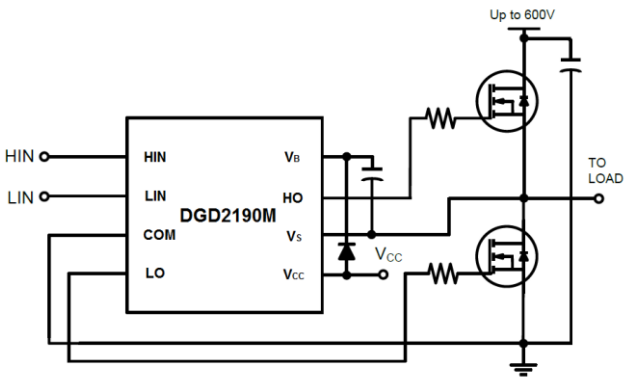
The DGD2190M is a high-voltage/high-speed gate driver capable of driving N-Channel MOSFETs and IGBTs in a half bridge configuration. High-voltage processing techniques enable the DGD2190M's high-side to switch to 600V in a bootstrap operation under high dV/dt conditions.

The DGD2190M logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) for easy interfacing with controlling devices. The driver outputs feature high pulse current buffers designed for minimum driver cross conduction.

The DGD2190M is offered in the SO-8 package and operates over an extended -40°C to +125°C temperature range.

Applications

- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers



Typical Configuration

Features

- Floating High-Side Driver in Bootstrap Operation to 600V
- Drives Two N-Channel MOSFETs or IGBTs in a Half-Bridge Configuation
- Output Drivers Capable of 4.5A/4.5A Typ. Sink/Source
- Logic Input (HIN and LIN) 3.3V Capability
- Schmitt Triggered Logic Inputs with Internal Pull-Down
- Undervoltage Lockout for High and Low-Side Drivers
- Extended Temperature Range: -40°C to +125°C
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q101, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.**
- **https://www.diodes.com/quality/product-definitions/**

Mechanical Data

- Case: SO-8 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 e3
- Weight: 0.075 grams (Approximate)



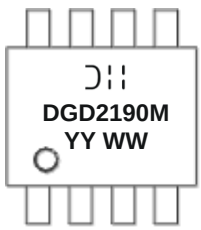
SO-8
Top View

Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
DGD2190MS8-13	DGD2190M	13	12	2,500

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

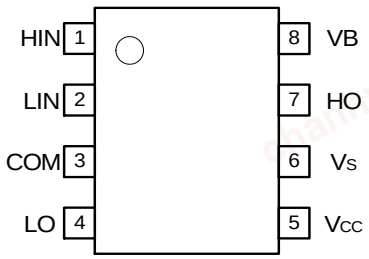


= Manufacturer's Marking
DGD2190M = Product Type Marking Code
YY = Year (ex: 19 = 2019)
WW = Week (01 to 53)

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Pin Diagrams

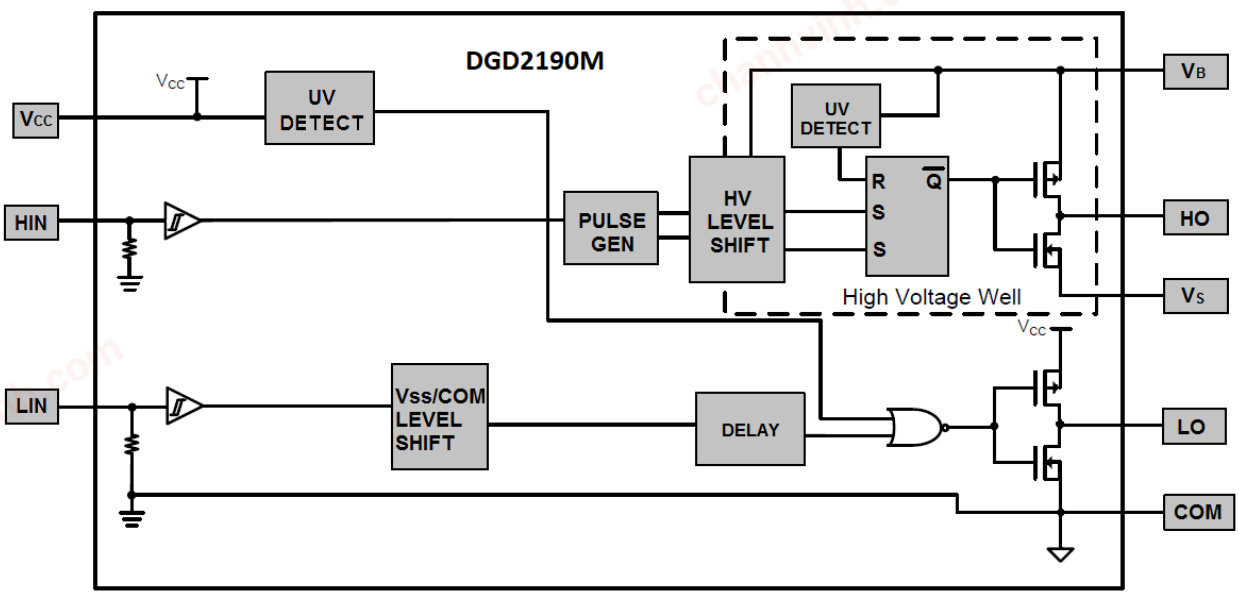


Top View: SO-8

Pin Descriptions

Pin Number	Pin Name	Function
1	HIN	Logic Input for High-side Gate Driver Output, in Phase with HO
2	LIN	Logic Input for Low-side Gate Driver Output, in Phase with LO
3	COM	Low-Side and Logic Return
4	LO	Low-Side Gate Drive Output
5	V_{CC}	Low-Side and Logic Fixed Supply
6	V_S	High-Side Floating Supply Return
7	HO	High-Side Gate Drive Output
8	V_B	High-Side Floating Supply

Functional Block Diagram



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Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-Side Floating Supply Voltage	V_B	-0.3 to +624	V
High-Side Floating Supply Offset Voltage	V_S	V_B -24 to V_B +0.3	V
High-Side Floating Output Voltage	V_{HO}	V_S -0.3 to V_B +0.3	V
Offset Supply Voltage Transient	dV_S / dt	50	V/ns
Low-Side and Logic Fixed Supply Voltage	V_{CC}	-0.3 to +24	V
Low-Side Output Voltage	V_{LO}	-0.3 to V_{CC} +0.3	V
Logic Input Voltage (HIN and LIN)	V_{IN}	-0.3 to V_{CC} +0.3	V

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	P_D	0.625	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction to Case (Note 5)	$R_{\theta JC}$	45	°C/W
Operating Temperature	T_J	+150	°C
Storage Temperature Range	T_{STG}	-55 to +150	

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High-Side Floating Supply Absolute Voltage	V_B	V_S +10	V_S +20	V
High-Side Floating Supply Offset Voltage	V_S	(Note 6)	600	V
High-Side Floating Output Voltage	V_{HO}	V_S	V_B	V
Low-Side Fixed Supply Voltage	V_{CC}	10	20	V
Low-Side Output Voltage	V_{LO}	0	V_{CC}	V
Logic Input Voltage (HIN and LIN)	V_{IN}	0	5	V
Ambient Temperature	T_A	-40	+125	°C

Notes: 5. When mounted on a standard JEDEC 2-layer FR-4 board.
6. Logic operation for V_S of -5V to +600V.

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DC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, @T_A = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Logic “1” Input Voltage (Note 8)	V_{IH}	2.5	—	—	V	V_{CC} = 10V to 20V
Logic “0” Input Voltage (Note 8)	V_{IL}	—	—	0.8	V	V_{CC} = 10V to 20V
High Level Output Voltage, V_{BIAS} - V_O	V_{OH}	—	—	0.1	V	I_O = 0mA
Low Level Output Voltage, V_O	V_{OL}	—	—	0.035	V	I_O = 0mA
Offset Supply Leakage Current	I_{LK}	—	—	50	µA	V_B = V_S = 600V
Quiescent V_{BS} Supply Current	I_{BSQ}	—	45	80	µA	V_{IN} = 0V or 5V
Quiescent V_{CC} Supply Current	I_{CCQ}	—	75	200	µA	V_{IN} = 0V or 5V
Logic “1” Input Bias Current	I_{IN+}	—	25	50	µA	V_{IN} = 5V
Logic “0” Input Bias Current	I_{IN-}	—	1.0	2.0	µA	V_{IN} = 0V
V_{BS} Supply Undervoltage Positive Going Threshold	V_{BSUV+}	7.6	8.4	9.8	V	—
V_{BS} Supply Undervoltage Negative Going Threshold	V_{BSUV-}	6.9	7.8	9.0	V	—
V_{CC} Supply Undervoltage Positive Going Threshold	V_{CCUV+}	7.6	8.4	9.8	V	—
V_{CC} Supply Undervoltage Negative Going Threshold	V_{CCUV-}	6.9	7.8	9.0	V	—
V_{CC} and V_{BS} Undervoltage Hysteresis	V_{CCUVH}	—	0.6	—	V	—
	V_{BSUVH}	—	0.6	—	V	—
Output High Short Circuit Pulsed Current	I_{O+}	3.5	4.5	—	A	V_O = 0V, PW ≤ 10ms
Output Low Short Circuit Pulsed Current	I_{O-}	3.5	4.5	—	A	V_O = 15V, PW ≤ 10ms

Notes:
7. The V_{IN} and I_{IN} parameters are applicable to the two logic pins; HIN and LIN. The V_O and I_O parameters are applicable to the respective output pins: HO and LO.
8. For optimal operation, it is recommended that the input pulses (HIN and LIN) should have a minimum amplitude of 2.5V with a minimum pulse width of 280ns.

AC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, C_L = 1000pF, @T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Turn-On Propagation Delay	t_{ON}	—	140	200	ns	V_S = 0V
Turn-Off Propagation Delay	t_{OFF}	—	140	200	ns	V_S = 0V
Delay Matching, HO & LO Turn On/Off	t_{DM}	—	—	50	ns	—
Turn-On Rise Time	t_R	—	25	50	ns	V_S = 0V
Turn-Off Fall Time	t_F	—	20	45	ns	V_S = 0V

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Timing Waveforms

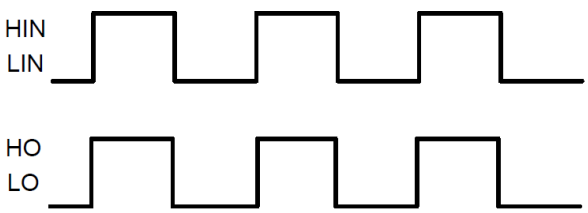


Figure 1. Input / Output Timing Diagram

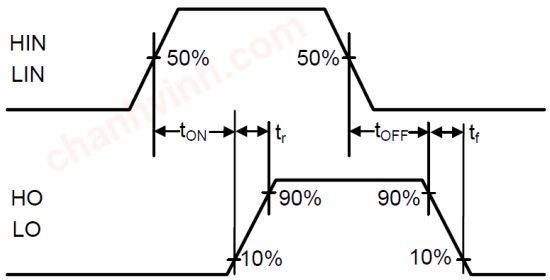


Figure 2. Switching Time Waveform Definitions

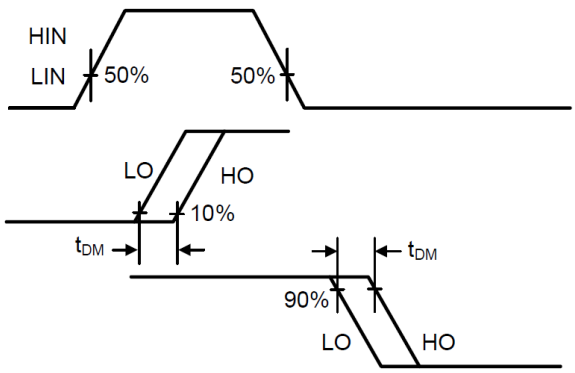


Figure 3. Delay Matching Waveform Definitions

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Typical Performance Characteristics (Vcc=15V, @T_A = +25°C, unless otherwise specified.)

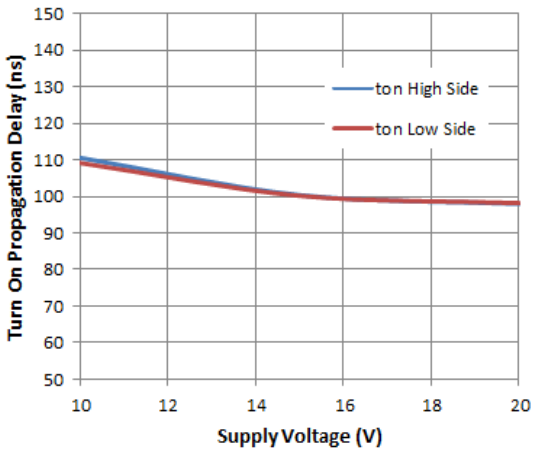


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

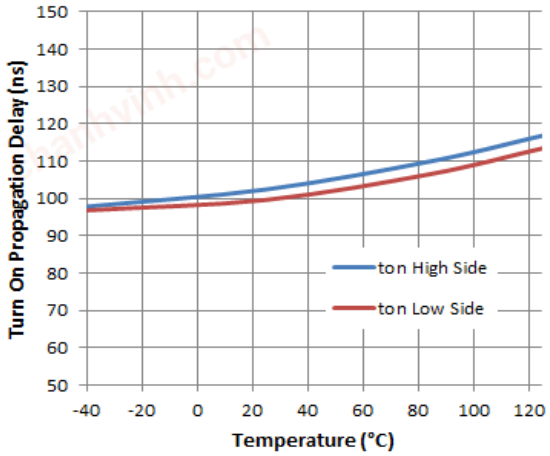


Figure 5. Turn-on Propagation Delay vs. Temperature

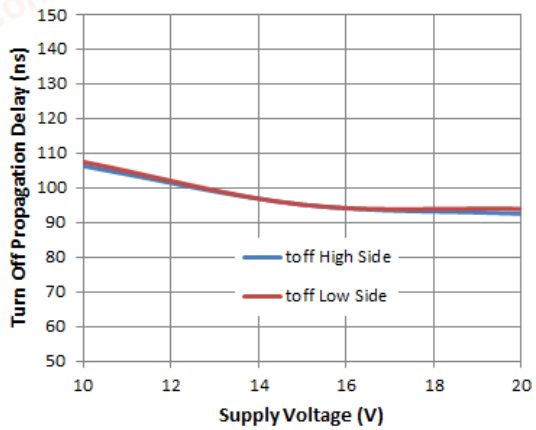


Figure 6. Turn-off Propagation Delay vs. Supply Voltage

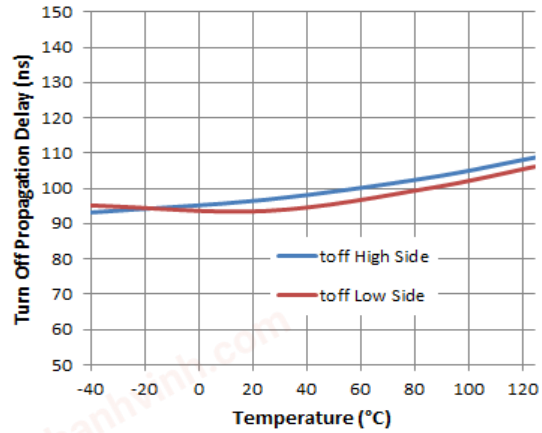


Figure 7. Turn-off Propagation Delay vs. Temperature

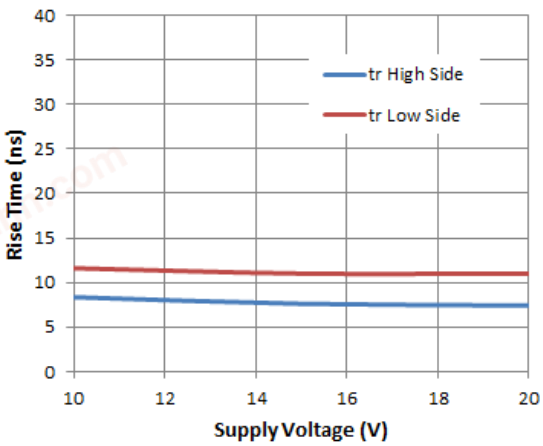


Figure 8. Rise Time vs. Supply Voltage

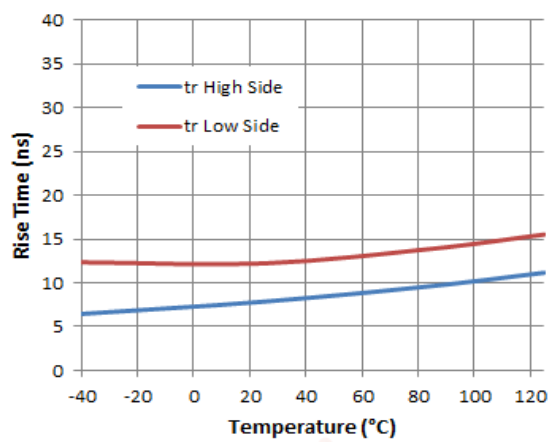


Figure 9. Rise Time vs. Temperature

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Typical Performance Characteristics (continued) (@T_A = +25°C, unless otherwise specified.)

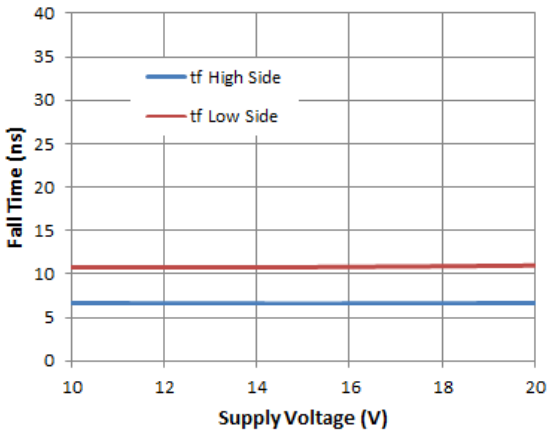


Figure 10. Fall Time vs. Supply Voltage

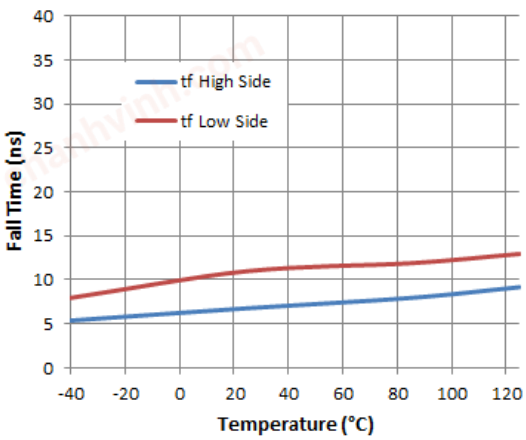


Figure 11. Fall Time vs. Temperature

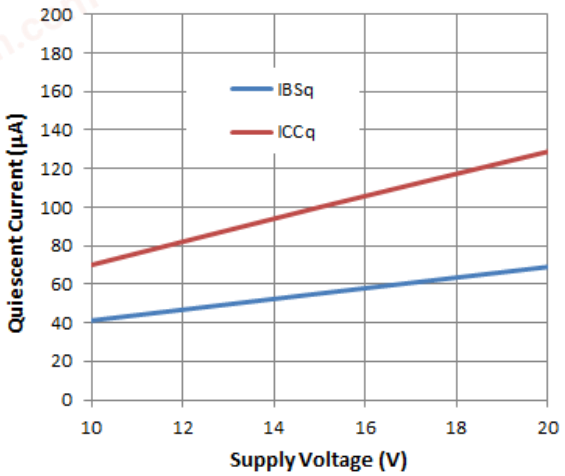


Figure 12. Quiescent Current vs. Supply Voltage

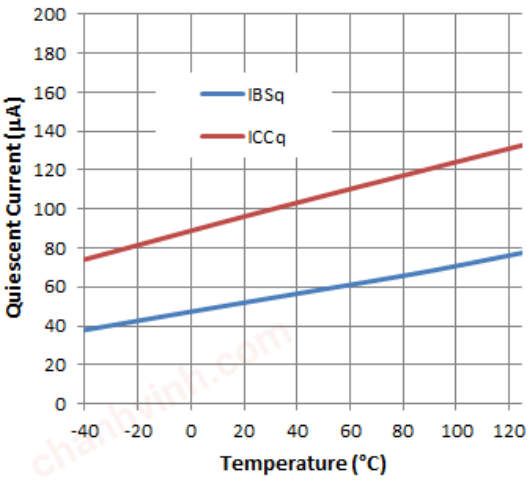


Figure 13. Quiescent Current vs. Temperature

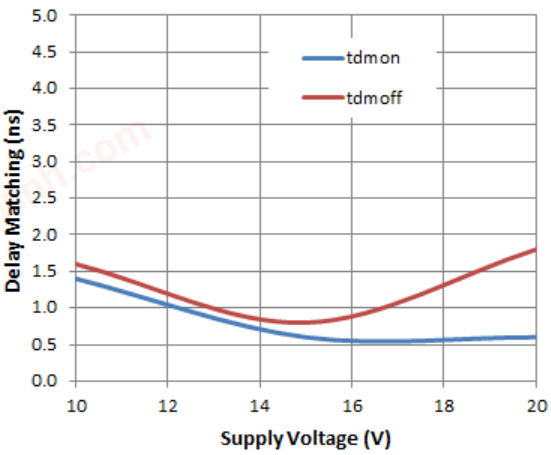


Figure 14. Delay Matching vs. Supply Voltage

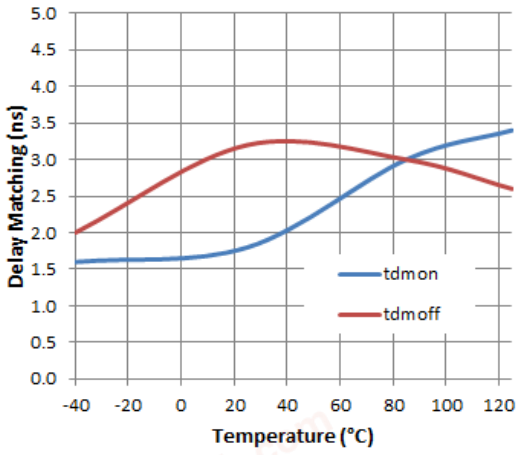


Figure 15. Delay Matching vs. Temperature

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Typical Performance Characteristics (continued) (@T_A = +25°C, unless otherwise specified.)

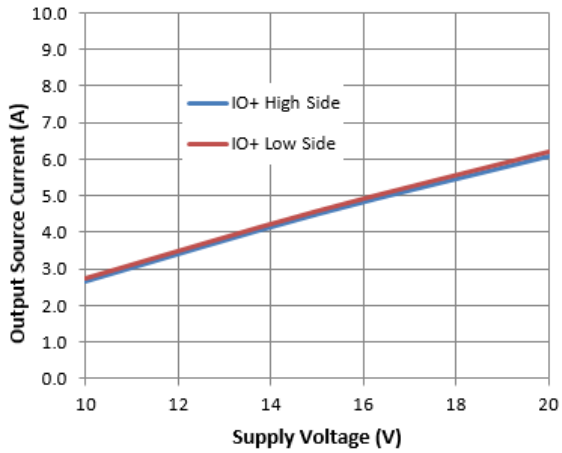


Figure 16. Output Source Current vs. Supply Voltage

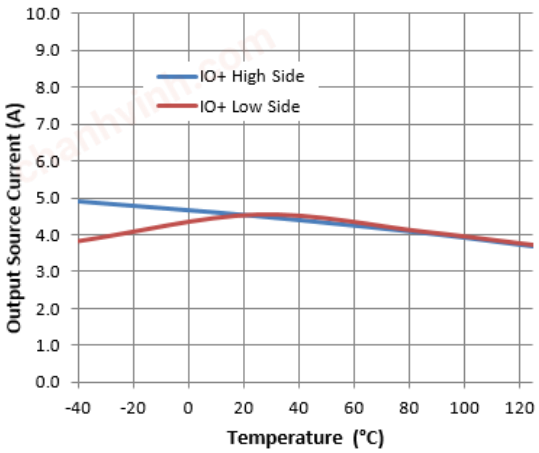


Figure 17. Output Source Current vs. Temperature

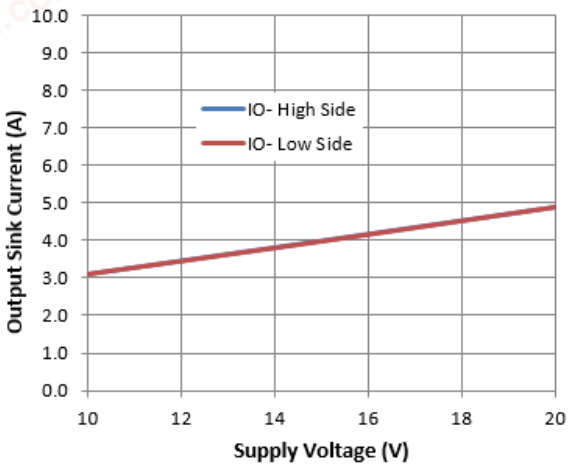


Figure 18. Output Sink Current vs. Supply Voltage

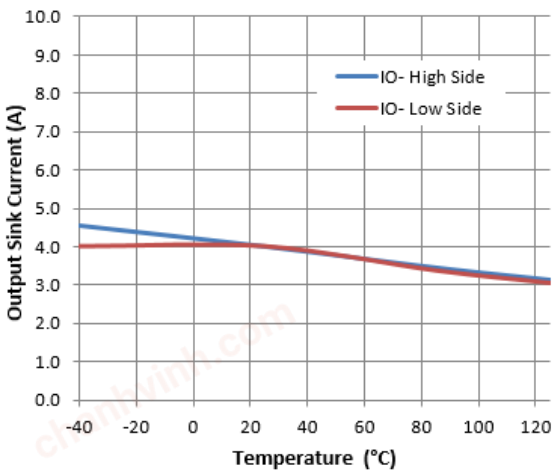


Figure 19. Output Sink Current vs. Temperature

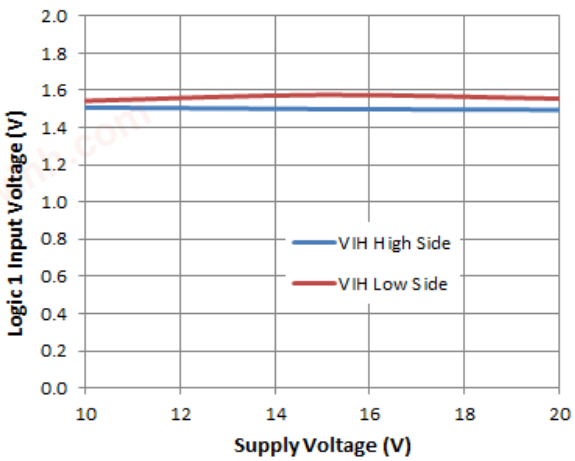


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

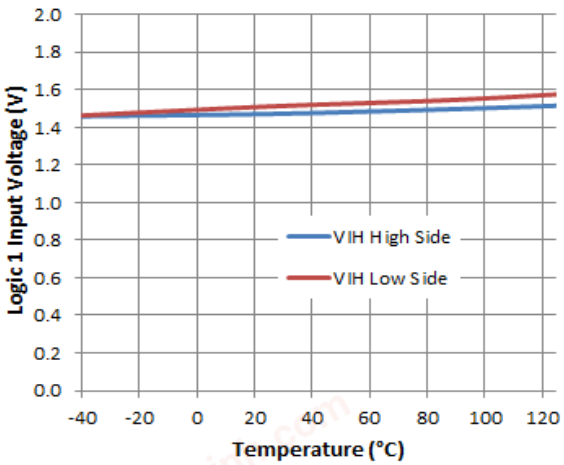


Figure 21. Logic 1 Input Voltage vs. Temperature

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Typical Performance Characteristics (continued) (@T_A = +25°C, unless otherwise specified.)

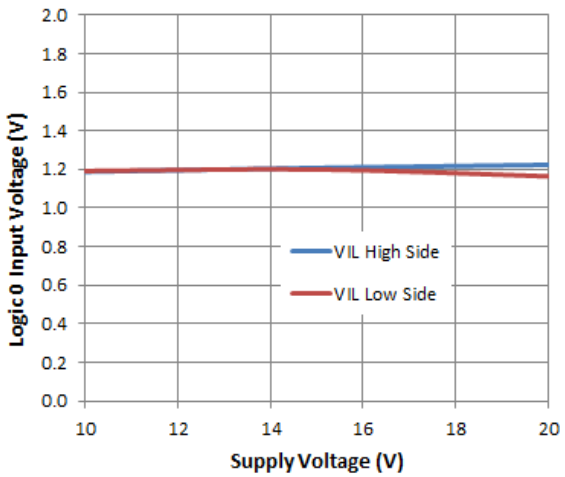


Figure 22. Logic 0 Input Voltage vs. Supply Voltage

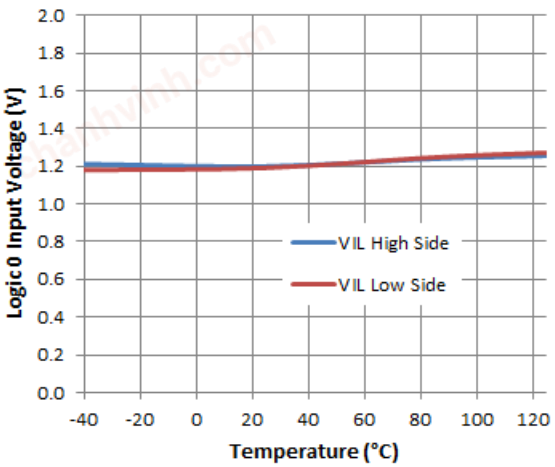


Figure 23. Logic 0 Input Voltage vs. Temperature

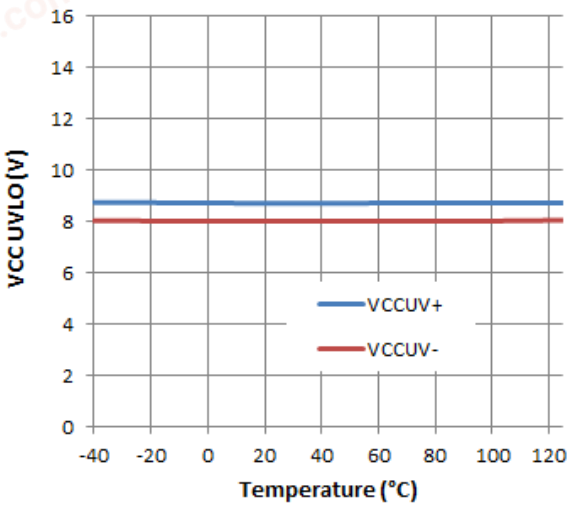


Figure 24. VCC UVLO vs. Temperature

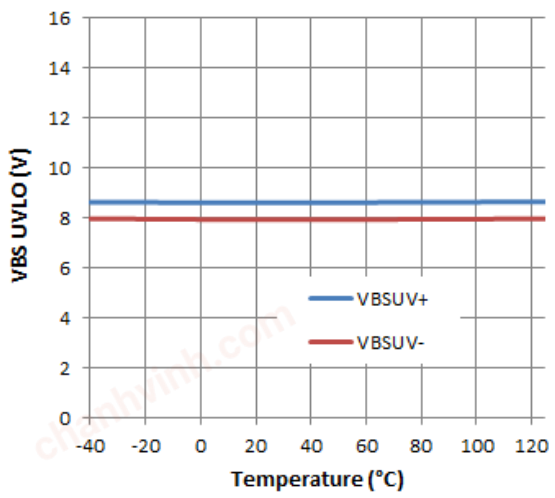


Figure 25. VBS UVLO vs. Temperature

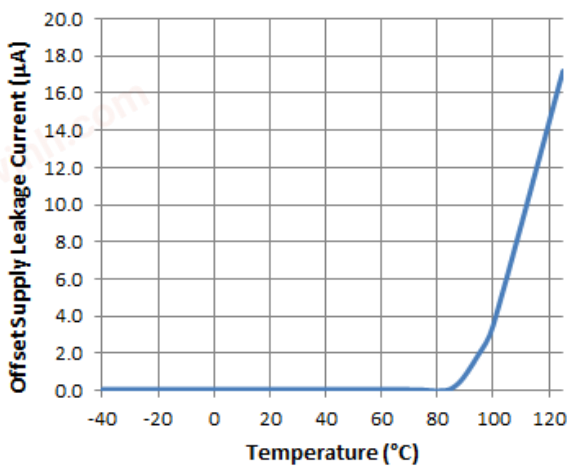


Figure 26. Offset Supply Leakage Current vs. Temperature

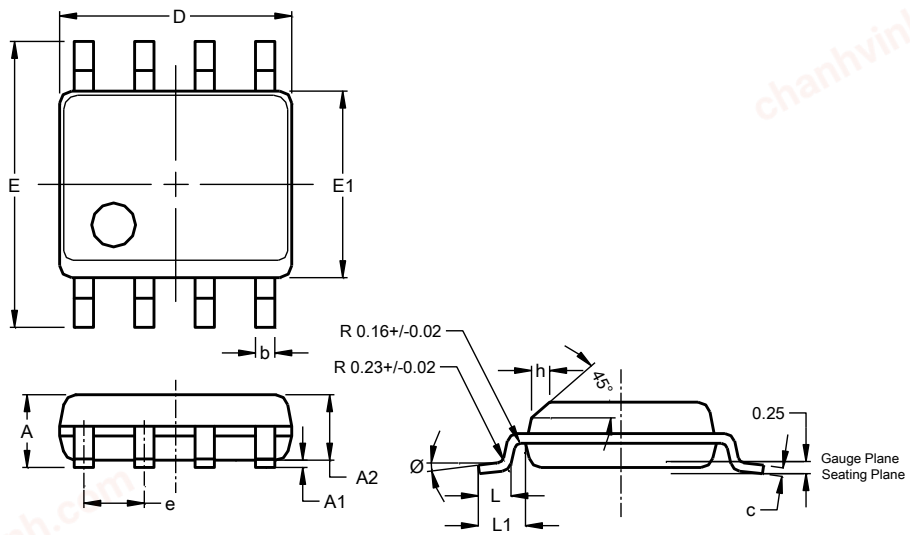
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Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8 (Type TH)

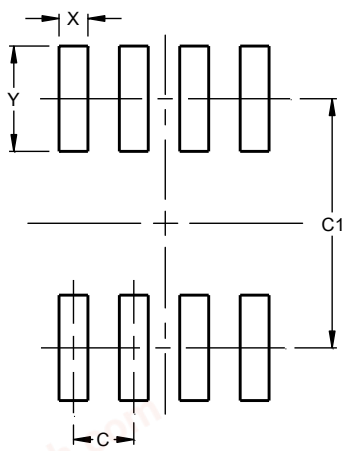


SO-8 (Type TH)			
Dim	**Min**	**Max**	**Typ**
A	1.35	1.75	–
A1	0.10	0.25	–
A2	–	–	1.45
b	0.35	0.51	–
c	0.190	0.248	–
D	4.80	5.00	4.90
E	5.80	6.20	6.00
E1	3.80	4.00	3.90
e	–	–	1.27
h	0.25	0.50	–
L	0.41	1.27	–
L1	–	–	1.04
Ø	0°	8°	–
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8 (Type TH)



Dimensions	Value (in mm)
C	1.27
C1	5.20
X	0.60
Y	2.20

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

A. Life support devices or systems are devices or systems which:

1. are intended to implant into the body, or
2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

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